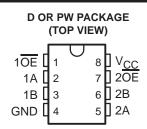
- **5**-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description/ordering information

The SN74CBTS3306 features independent line switches with Schottky diodes on the I/Os to clamp undershoot. Each switch is disabled when the associated output-enable (\overline{OE}) input is high.



ORDERING INFORMATION

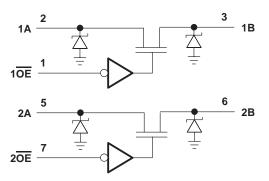
TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC – D	Tube	SN74CBTS3306D	00000
		Tape and reel	SN74CBTS3306DR	CR306
	TSSOP – PW	Tube	SN74CBTS3306PW	CR306
		Tape and reel	SN74CBTS3306PWR	CK300

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each bus switch)

INPUT OE	FUNCTION
L	A port = B port
Н	Disconnect

logic diagram (positive logic)





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SN74CBTS3306 DUAL FET BUS SWITCH WITH SCHOTTKY DIODE CLAMPING

SCDS029I – JANUARY 1996 – REVISED JANUARY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1) –	
Continuous channel current	
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	
PW package	149°C/W
Storage temperature range, T _{stg} 65	°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
Т _А	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
	A or B inputs						-0.7	
VIK	Control inputs	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$				-1.2	V
	۱ _{IL}	$V_{CC} = 5.5 V,$	$V_{I} = GND$				-1	•
Ι	IН	V _{CC} = 5.5 V,	V _I = 5.5 V				150	μA
ICC		V _{CC} = 5.5 V,	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ
∆ICC§	Control inputs	$V_{CC} = 5.5 V,$	One input at 3.4 V,	Other inputs at V_{CC} or GND			2.5	mA
Ci	Control inputs	$V_I = 3 V \text{ or } 0$				5		pF
Cio(OFF)		V _O = 3 V or 0,	$\overline{OE} = V_{CC}$			6		pF
ron¶		$V_{CC} = 4 V$, TYP at $V_{CC} = 4 V$	V _I = 2.4 V,	l _l = 15 mA		14	20	
			N O	lj = 64 mA		5	7	Ω
-		V _{CC} = 4.5 V V _I = 0	V] = 0	l _l = 30 mA		5	7	
			V _I = 2.4 V,	lı = 15 mA		10	15	

[‡] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

I Measured by the voltage drop between the A and B pin at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) pins.



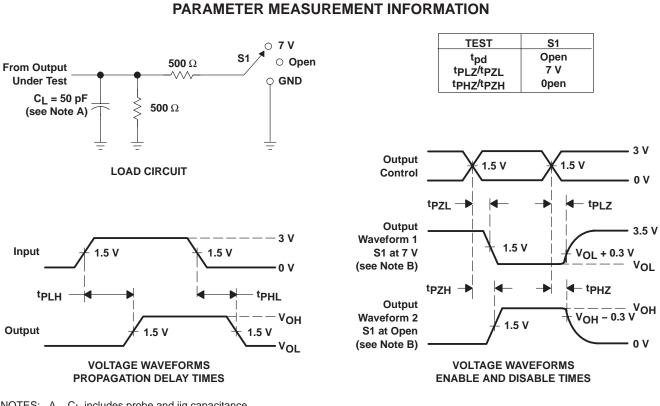
SN74CBTS3306 DUAL FET BUS SWITCH ITH SCHOTTKY DIODE CLAMPING

SCDS029I - JANUARY 1996 - REVISED JANUARY 2004

switching characteristics over recommended operating free-air temperature range, CL = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER		FROM	TO	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX		
t _{pd} †		A or B	B or A		0.35		0.25	ns
t _{en}		OE	A or B		5.6	1.8	5	ns
^t dis		OE	A or B		4.6	1	4.3	ns

[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl $_{7}$ and tpH $_{7}$ are the same as t_{dis}.
- F. tpzL and tpzH are the same as ten.
- G. tPHL and tPLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

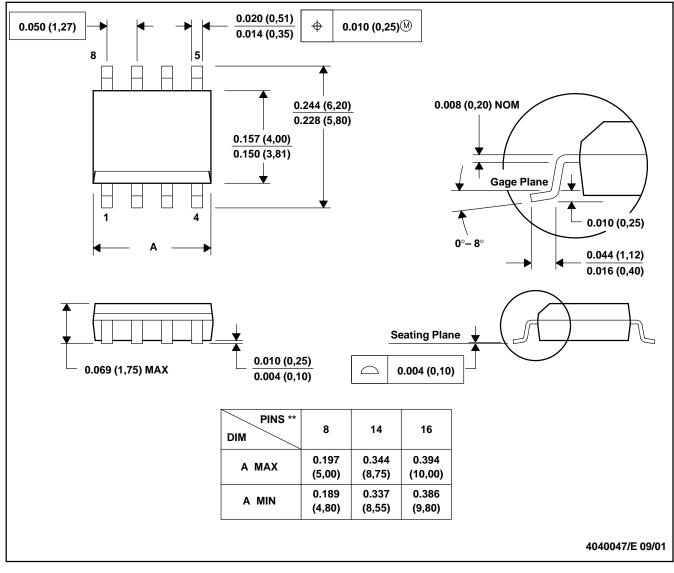


MECHANICAL DATA

MSOI002B - JANUARY 1995 - REVISED SEPTEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

D (R-PDSO-G**) 8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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